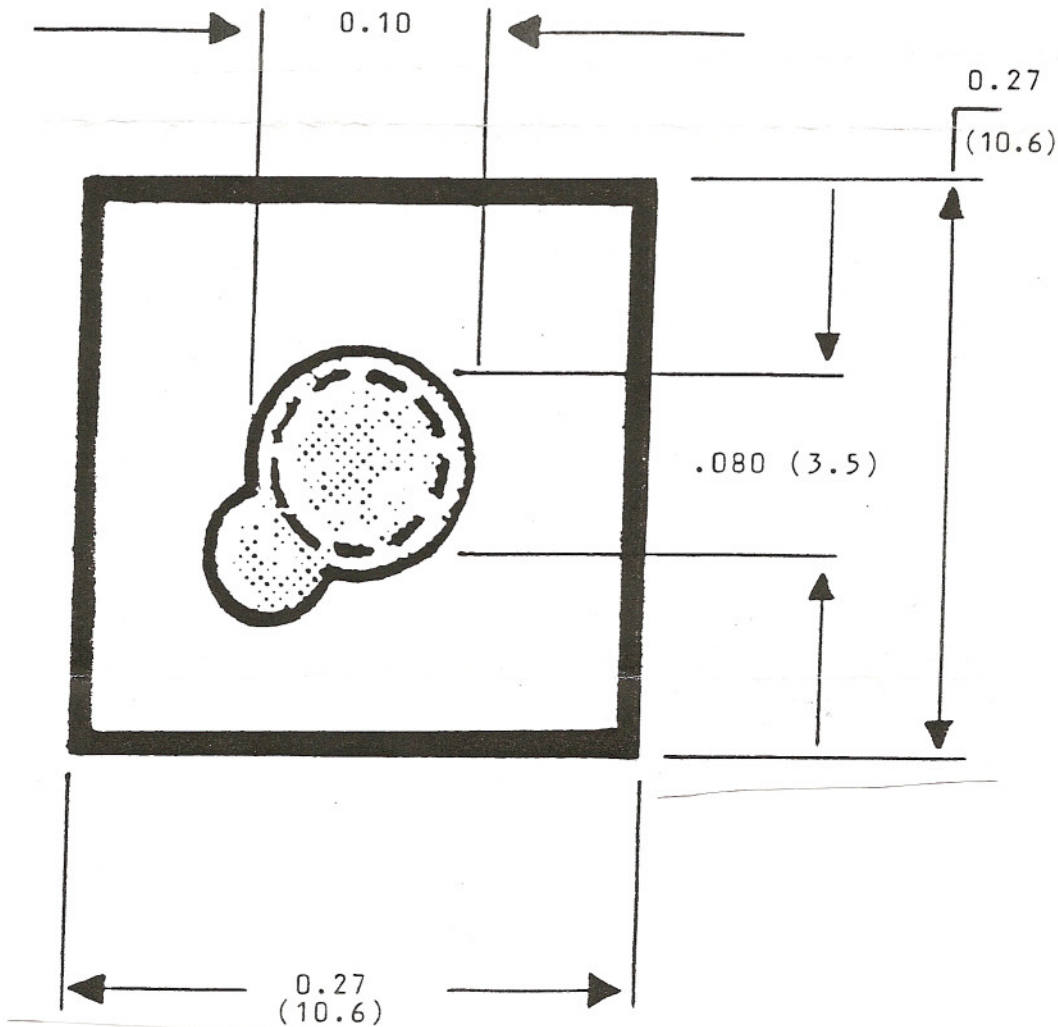




# Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423  
 Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Top Material:**  
**Backside Material:**  
**Bond Pad Size:**  
**Backside Potential:**  
**Mask Ref:**

APPROVED BY:MG

DIE SIZE :10x10

DATE: 1/20/09

MFG:Hewlett Packard

THICKNESS:

P/N:HSMS-0002